

BERGSTAK® 0.8mm CONNECTORS

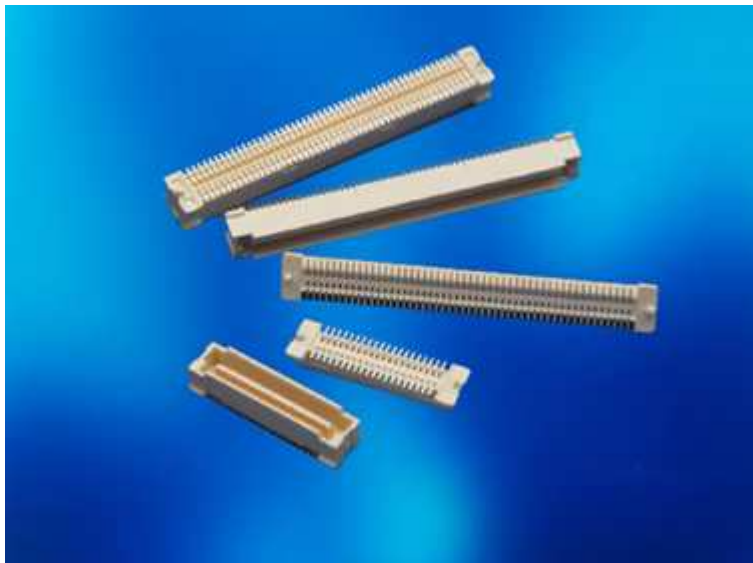


Betty Tan



Bergstak 0.8mm pitch connector

- Based on the number of positions, we have classified the parts into two categories,
 - Low pin count, from 40pos to 120pos
 - High pin count, from 140pos to 200pos
- Based on the height of the housing, we have further divided the parts into different classes,
 - For plug, P1 to P4, the height from 4.7mm to 7.7mm
 - For receptacle, R1 to R3, the height from 3.7mm to 11.7mm



Mated Height Combinations

		HEADERS				
		1	2	3	4	
RECEPTACLES	1	 3.70 mm (0.146 in.)	 5.00 mm (0.197 in.)	 6.00 mm (0.236 in.)	 7.00 mm (0.276 in.)	 8.00 mm (0.315 in.)
	2	 7.70 mm (0.30 in.)	 9.00 mm (0.354 in.)	 10.00 mm (0.394 in.)	 11.00 mm (0.433 in.)	 12.00 mm (0.472 in.)
	3	 11.70 mm (0.461 in.)	 13.00 mm (0.512 in.)	 14.00 mm (0.551 in.)	 15.00 mm (0.591 in.)	 16.00 mm (0.630 in.)

Plug,

61083-AABCDEFF

Receptacle,

61082-AABCDEFF

AA is the number of position

B is the housing height

C is the plating option

D is the polarization peg option

E is the packaging option

FF is the leadfree option

■ Notebooks / Desktop PCs / Workstations

- CPU Modules
- Graphics Cards
- CardBus Transition boards
- Memory expansion modules
- Modem cards

■ Embedded PCs

■ Networking equipment

- Routers
- Switches
- Servers

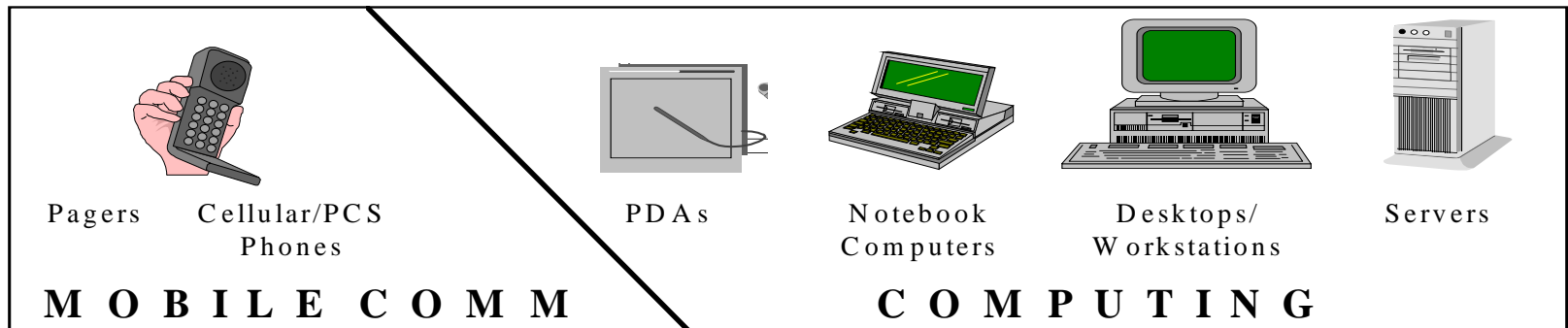
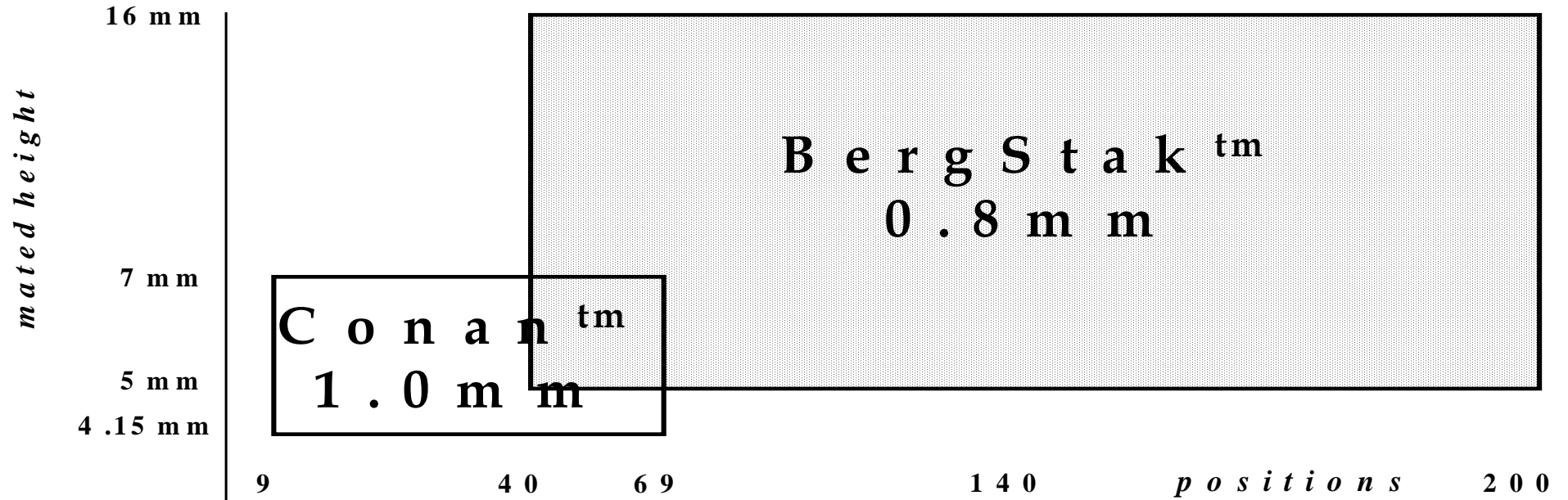
Mated heights	5.0 mm (0.197 in.), 6.0 mm (0.236 in). 7.0 mm (0.276 in.), 8.0 mm (0.315 in). 9.0 mm (0.354 in.), 10.0 mm (0.394 in). 11.0 mm (0.433 in.), 12.0 mm (0.472 in). 13.0 mm (0.512 in.), 14.0 mm (0.551 in). 15.0 mm (0.591 in.), 16.0 mm (0.630 in).
High Contact Density	Dual row at 0.8 mm (0.031 in.) pitch. Linear density of 25 contacts/cm or 64 contacts/inch
Robust Design	<ul style="list-style-type: none"> -Blade-on-beam contact interface resists "peeling" damage -Precious metal finish in contact areas provides reliable electrical performance -Tin-lead over nickel in solder areas produces excellent solder joints -Connector polarization and ample lead in angles produce easy repeatable mating -Compatible with infrared and convection reflow soldering
Packaging option	Extruded tubes or tape-and reel for automated handling. Optional covers for vacuum pickup

Materials	<ul style="list-style-type: none">■ Housing<ul style="list-style-type: none">- Glass filled LCP (UL94 V-0)■ Contact base metal<ul style="list-style-type: none">- Copper alloy■ Contact area finish<ul style="list-style-type: none">- Gold or Gold flash over palladium-nickel over nickel■ Solder area finish<ul style="list-style-type: none">- Tin-lead or matte pure tin over nickel
Environmental	<ul style="list-style-type: none">■ Temperature range: -40°C to +85°C■ High temperature life: 95 +/- 5°C for 96 hours■ Humidity: 90-95% relative humidity for 96hours■ SO2 gas exposure: 10 ppm H2 density at 90% relative humidity and Ambient Temperature 40 +/-2°C for 24 hours

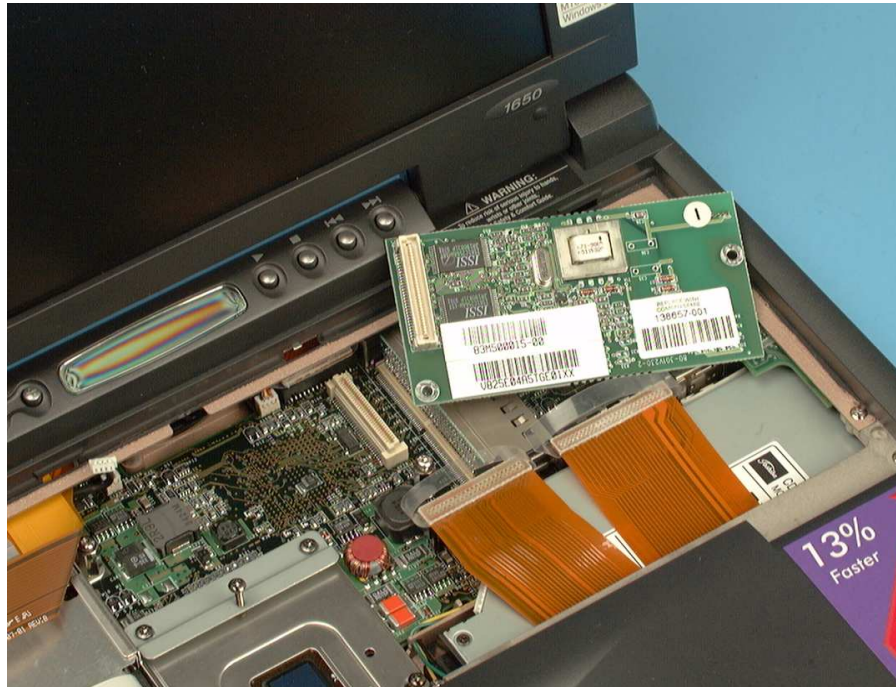
Mechanical Performance	<ul style="list-style-type: none">■ Durability: 100 cycles■ Mating force: 0.9N (90 gramf) maximum/contact■ Un-mating force: 0.1N (10 gramf) minimum/contact
Electrical Performance	<ul style="list-style-type: none">■ Insulation resistance:<ul style="list-style-type: none">- Initial: 500 MΩ minimum- After test: 100 MΩ minimum■ Current rating:<ul style="list-style-type: none">- 0.5 amp/contact■ Contact resistance:<ul style="list-style-type: none">- Initial: 30 MΩ maximum- After test: 50 MΩ maximum■ Voltage rating:<ul style="list-style-type: none">- 100 V AC

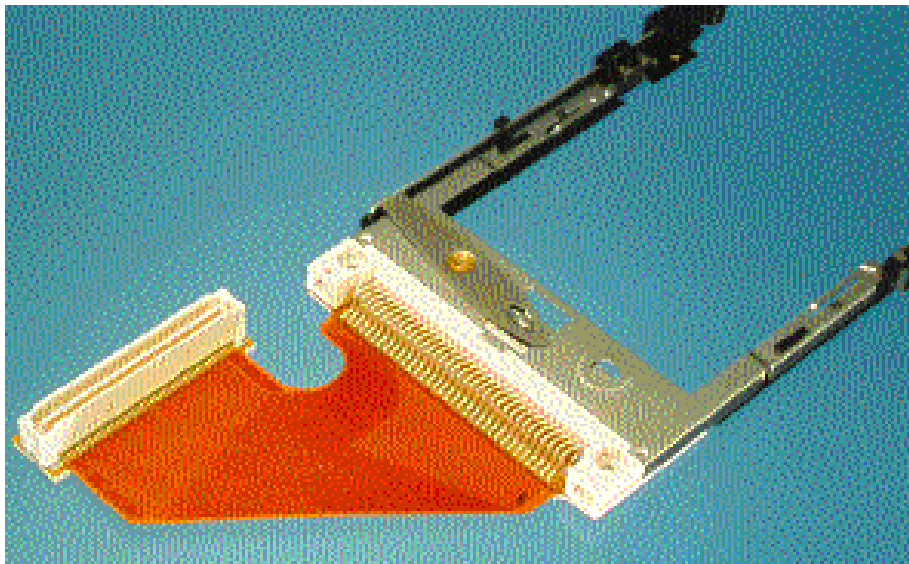
Specification	<ul style="list-style-type: none">■ GS-12-148 BergStak 0.8mm Product Specification
Approvals and Certifications	<ul style="list-style-type: none">■ UL certificate, file no. E66906■ CSA, file no. LR46923
Packaging	<ul style="list-style-type: none">■ Tape and reel (with or without pickup cap)■ Tubes (with or without pickup caps)

Target Market and Applications

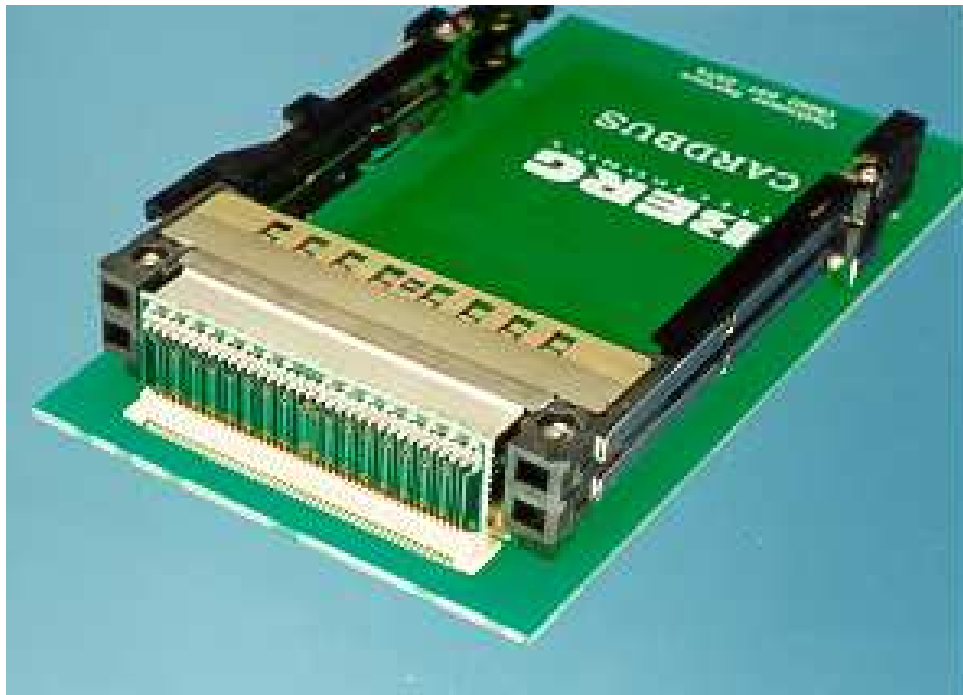


- Mezzanine board in notebook PC





Flexible Circuit

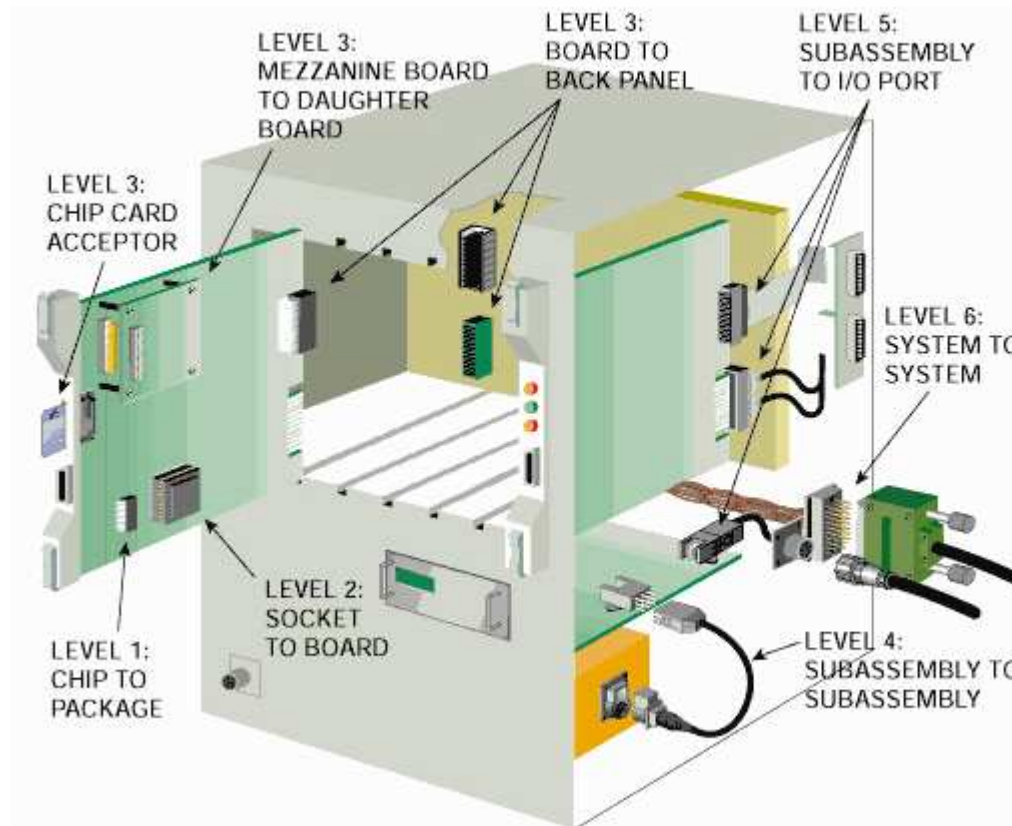


■ Card Bus transition board

Packaging Level For Product



Bergstak 0.8mm is a product at packaging Level 3 : Board to Board



- **Customer Drawing**
 - **61082c.PDF**
 - **61083c.PDF**

- **Datasheet**
 - **SP BSTAK 0507E**

- **Packaging Specification**
 - **GS-14-551**

- **Product Specification**
 - **GS-12-148**

- **3D Models (ProE & IGES) – Web Site**

Use web link www.fciconnect.com/bergstak to obtain product drawings and additional technical information.



Thank You

